

512K x 8 LOW VOLTAGE, ULTRA LOW POWER CMOS STATIC RAM

FEBRUARY 2012

FEATURES

- High-speed access time: 35, 45, 55 ns
- CMOS low power operation
 - 36 mW (typical) operating
 - 9 μ W (typical) CMOS standby
- TTL compatible interface levels
- Single power supply
 - 1.65V – 2.2V V_{DD} (IS62WV5128DALL)
 - 2.3V – 3.6V V_{DD} (IS62WV5128DBLL)
- Fully static operation: no clock or refresh required
- Three state outputs
- Industrial and Automotive temperature support
- Lead-free available

DESCRIPTION

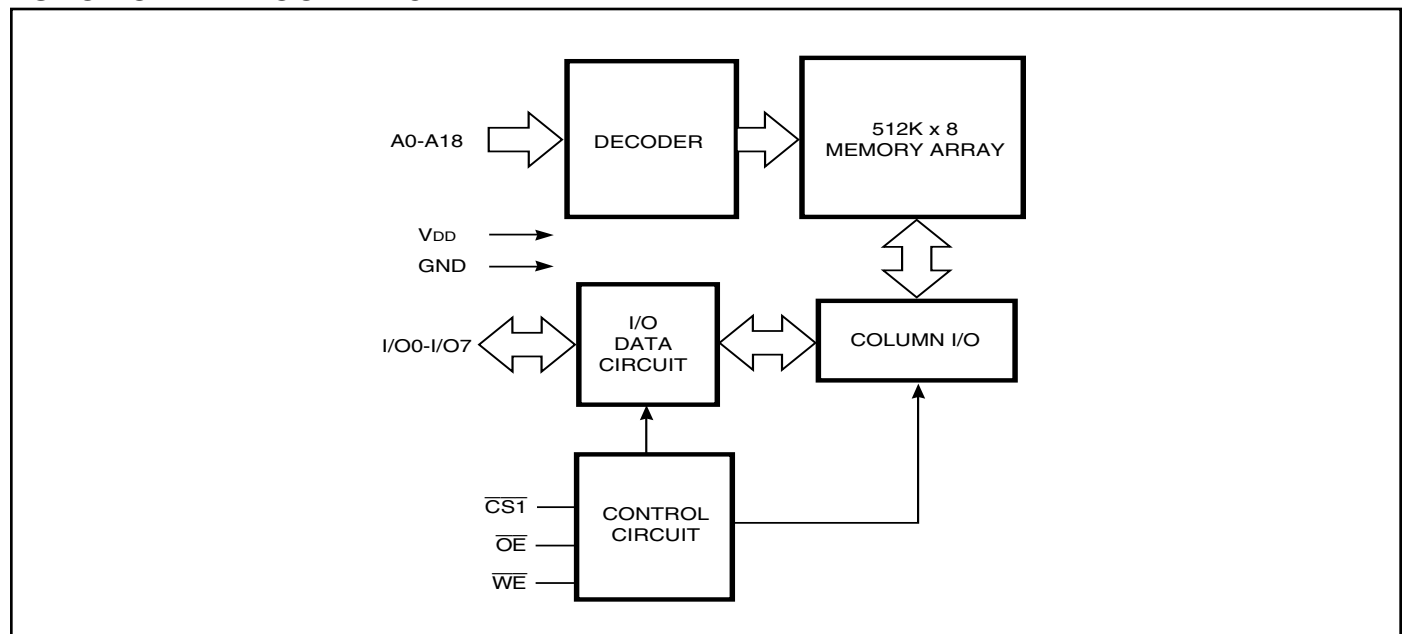
The *ISSI* IS62WV5128DALL / IS62WV5128DBLL are high-speed, 4M bit static RAMs organized as 512K words by 8 bits. It is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields high-performance and low power consumption devices.

When $\overline{CS1}$ is HIGH (deselected) the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs. The active LOW Write Enable ($\overline{WE}$) controls both writing and reading of the memory.

The IS62WV5128DALL and IS62WV5128DBLL are packaged in the JEDEC standard 32-pin TSOP (TYPE I), 32-pin sTSOP (TYPE I), 32-pin TSOP (Type II), 32-pin SOP and 36-pin mini BGA.

FUNCTIONAL BLOCK DIAGRAM



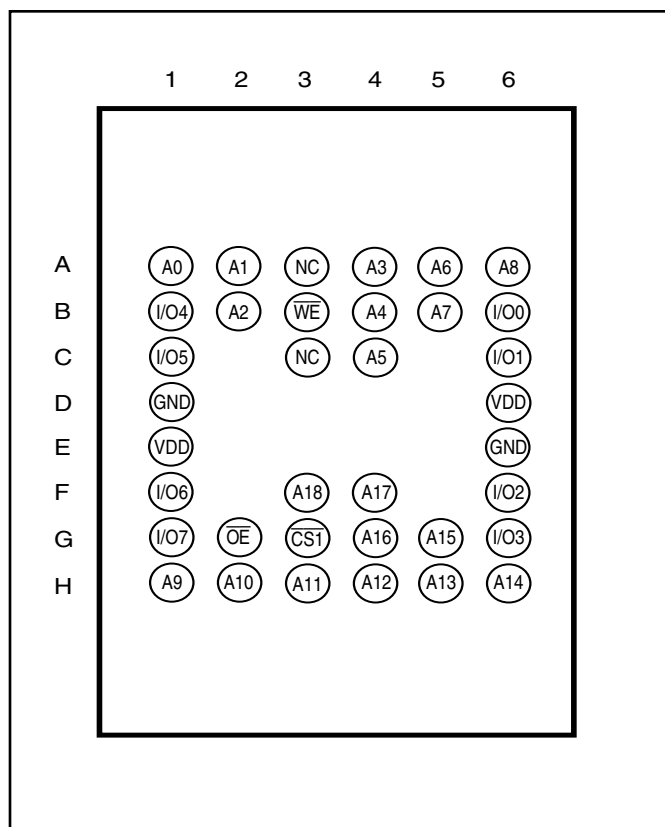
Copyright © 2012 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

Integrated Silicon Solution, Inc. does not recommend the use of any of its products in life support applications where the failure or malfunction of the product can reasonably be expected to cause failure of the life support system or to significantly affect its safety or effectiveness. Products are not authorized for use in such applications unless Integrated Silicon Solution, Inc. receives written assurance to its satisfaction, that:

- a.) the risk of injury or damage has been minimized;
- b.) the user assume all such risks; and
- c.) potential liability of Integrated Silicon Solution, Inc is adequately protected under the circumstances

PIN DESCRIPTIONS

A0-A18	Address Inputs
$\overline{\text{CS1}}$	Chip Enable 1 Input
$\overline{\text{OE}}$	Output Enable Input
$\overline{\text{WE}}$	Write Enable Input
I/O0-I/O7	Input/Output
NC	No Connection
V _{DD}	Power
GND	Ground

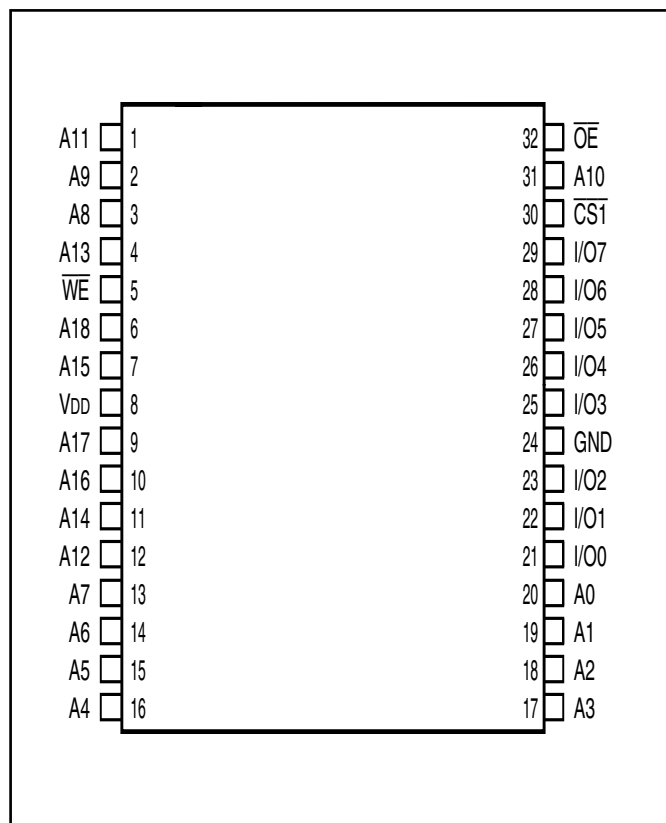
**36-pin mini BGA (B) (6mm x 8mm)
(Package Code B)**

PIN DESCRIPTIONS

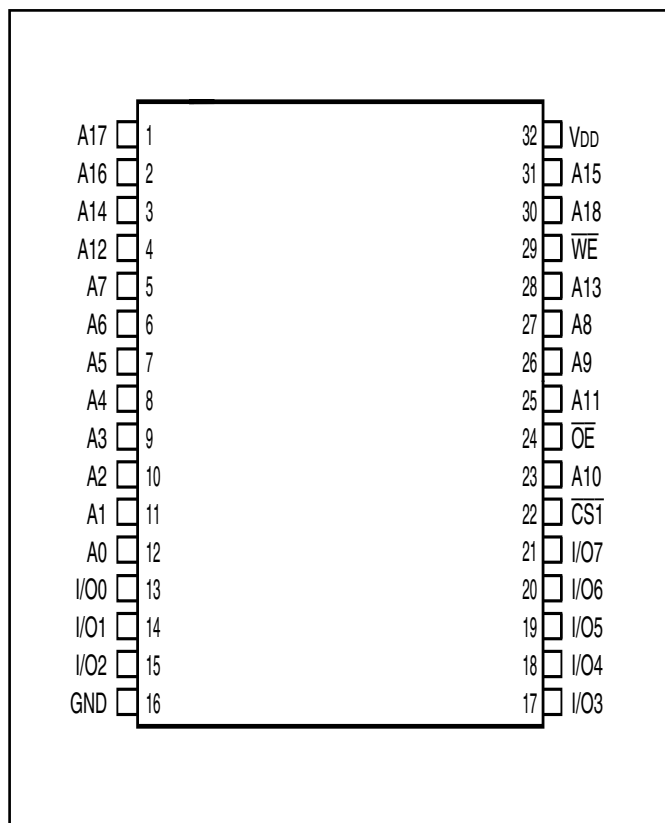
A0-A18	Address Inputs
CS1	Chip Enable 1 Input
OE	Output Enable Input
WE	Write Enable Input
I/O0-I/O7	Input/Output
VDD	Power
GND	Ground

PIN CONFIGURATION

32-pin TSOP (TYPE I), (Package Code T)
32-pin sTSOP (TYPE I) (Package Code H)



32-pin SOP (Package Code Q)
32-pin TSOP (TYPE II) (Package Code T2)



TRUTH TABLE

Mode	$\overline{WE}$	$\overline{CS1}$	$\overline{OE}$	I/O Operation	V _{DD} Current
Not Selected (Power-down)	X	H	X	High-Z	I _{SB1} , I _{SB2}
Output Disabled	H	L	H	High-Z	I _{CC}
Read	H	L	L	D _{OUT}	I _{CC}
Write	L	L	X	D _{IN}	I _{CC}

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Parameter	Value	Unit
V _{TERM}	Terminal Voltage with Respect to GND	−0.5 to V _{DD} + 0.5	V
V _{DD}	V _{DD} Relates to GND	−0.3 to 4.0	V
T _{STG}	Storage Temperature	−65 to +150	°C
P _T	Power Dissipation	1.0	W

Notes:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

CAPACITANCE^(1,2)

Symbol	Parameter	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	6	pF
C _{I/O}	Input/Output Capacitance	V _{OUT} = 0V	8	pF

Notes:

1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T_A = 25°C, f = 1 MHz, V_{DD} = 3.3V.

AC TEST CONDITIONS

Parameter	Unit (2.3V-3.6V)	Unit (3.3V $\pm$ 5%)	Unit (1.65V-2.2V)
Input Pulse Level	0.4V to $V_{DD} - 0.3V$	0.4V to $V_{DD} - 0.3V$	0.4V to $V_{DD} - 0.3V$
Input Rise and Fall Times	1V/ ns	1V/ ns	1V/ ns
Input and Output Timing and Reference Level (V_{Ref})	$V_{DD} / 2$	$\frac{V_{DD}}{2} + 0.05$	0.9V
Output Load	See Figures 1 and 2	See Figures 1 and 2	See Figures 1 and 2
R1 (Ω)	1005	1213	13500
R2 (Ω)	820	1378	10800
V_{TM} (V)	3.0V	3.3V	1.8V

AC TEST LOADS

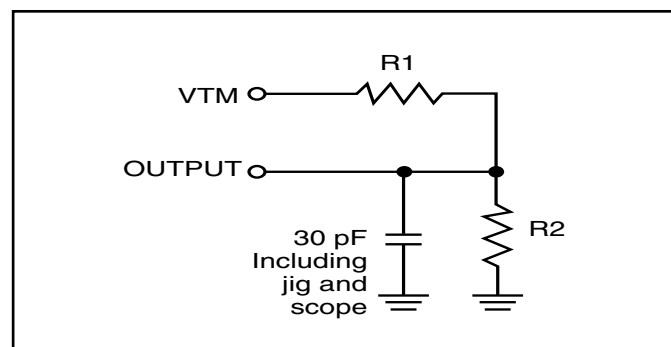


Figure 1.

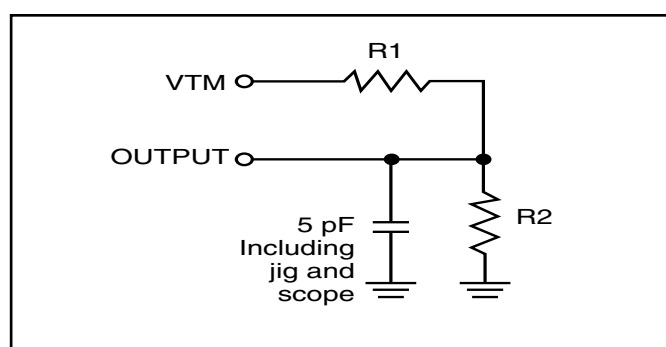


Figure 2.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

 $V_{DD} = 3.3V \pm 5\%$

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	$V_{DD} = \text{Min.}, I_{OH} = -1 \text{ mA}$	2.4	—	V
V_{OL}	Output LOW Voltage	$V_{DD} = \text{Min.}, I_{OL} = 2.1 \text{ mA}$	—	0.4	V
V_{IH}	Input HIGH Voltage		2	$V_{DD} + 0.3$	V
V_{IL}	Input LOW Voltage ⁽¹⁾		-0.3	0.8	V
I_{LI}	Input Leakage	$GND \leq V_{IN} \leq V_{DD}$	-1	1	μA
I_{LO}	Output Leakage	$GND \leq V_{OUT} \leq V_{DD}$, Outputs Disabled	-1	1	μA

Note:

- $V_{IL} (\text{min.}) = -0.3V \text{ DC}$; $V_{IL} (\text{min.}) = -2.0V \text{ AC}$ (pulse width < 10 ns). Not 100% tested.
 $V_{IH} (\text{max.}) = V_{DD} + 0.3V \text{ DC}$; $V_{IH} (\text{max.}) = V_{DD} + 2.0V \text{ AC}$ (pulse width < 10 ns). Not 100% tested.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

 $V_{DD} = 2.3V-3.6V$

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	$V_{DD} = \text{Min.}, I_{OH} = -1.0 \text{ mA}$	1.8	—	V
V_{OL}	Output LOW Voltage	$V_{DD} = \text{Min.}, I_{OL} = 2.1 \text{ mA}$	—	0.4	V
V_{IH}	Input HIGH Voltage		2.0	$V_{DD} + 0.3$	V
V_{IL}	Input LOW Voltage ⁽¹⁾		-0.3	0.8	V
I_{LI}	Input Leakage	$GND \leq V_{IN} \leq V_{DD}$	-1	1	μA
I_{LO}	Output Leakage	$GND \leq V_{OUT} \leq V_{DD}$, Outputs Disabled	-1	1	μA

Note:

- $V_{IL} (\text{min.}) = -0.3V \text{ DC}$; $V_{IL} (\text{min.}) = -2.0V \text{ AC}$ (pulse width < 10 ns). Not 100% tested.
 $V_{IH} (\text{max.}) = V_{DD} + 0.3V \text{ DC}$; $V_{IH} (\text{max.}) = V_{DD} + 2.0V \text{ AC}$ (pulse width < 10 ns). Not 100% tested.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

 $V_{DD} = 1.65V-2.2V$

Symbol	Parameter	Test Conditions	V_{DD}	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	$I_{OH} = -0.1 \text{ mA}$	1.65-2.2V	1.4	—	V
V_{OL}	Output LOW Voltage	$I_{OL} = 0.1 \text{ mA}$	1.65-2.2V	—	0.2	V
V_{IH}	Input HIGH Voltage		1.65-2.2V	1.4	$V_{DD} + 0.2$	V
$V_{IL}^{(1)}$	Input LOW Voltage		1.65-2.2V	-0.2	0.4	V
I_{LI}	Input Leakage	$GND \leq V_{IN} \leq V_{DD}$		-1	1	μA
I_{LO}	Output Leakage	$GND \leq V_{OUT} \leq V_{DD}$, Outputs Disabled		-1	1	μA

Note:

- $V_{IL} (\text{min.}) = -0.3V \text{ DC}$; $V_{IL} (\text{min.}) = -2.0V \text{ AC}$ (pulse width < 10 ns). Not 100% tested.
 $V_{IH} (\text{max.}) = V_{DD} + 0.3V \text{ DC}$; $V_{IH} (\text{max.}) = V_{DD} + 2.0V \text{ AC}$ (pulse width < 10 ns). Not 100% tested.

OPERATING RANGE (V_{DD})

Range	Ambient Temperature	V _{DD}	Speed
Commercial	0°C to +70°C	1.65V-2.2V	45ns
Industrial	-40°C to +85°C	1.65V-2.2V	55ns
Automotive	-40°C to +125°C	1.65V-2.2V	55ns

OPERATING RANGE (V_{DD})

Range	Ambient Temperature	V _{DD} (45 ns)	V _{DD} (35 ns)
Commercial	0°C to +70°C	2.3V-3.6V	3.3V±5%
Industrial	-40°C to +85°C	2.3V-3.6V	3.3V±5%

OPERATING RANGE (V_{DD})

Range	Ambient Temperature	V _{DD} (45 ns)
Automotive	-40°C to +125°C	2.3V-3.6V

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	Test Conditions		-35		-45		-55		Unit
				Min.	Max.	Min.	Max.	Min.	Max.	
I _{CC}	V _{DD} Dynamic Operating Supply Current	V _{DD} = Max.,	Com.	—	20	—	15	—	15	mA
		I _{OUT} = 0 mA, f = f _{MAX}	Ind.	—	25	—	20	—	20	
		$\overline{CE} = V_{IL}$	Auto.	—	30	—	25	—	25	
		V _{IN} ≥ V _{DD} - 0.3V, or V _{IN} ≤ 0.4V	typ. ⁽²⁾	—	10	—	—	—	—	
I _{CC1}	Operating Supply Current	V _{DD} = Max.,	Com.	—	3	—	3	—	3	mA
		I _{OUT} = 0 mA, f = 0	Ind.	—	3	—	3	—	3	
		$\overline{CE} = V_{IL}$	Auto.	—	3	—	3	—	3	
		V _{IN} ≥ V _{DD} - 0.3V, or V _{IN} ≤ 0.4V	—	—	—	—	—	—	—	
I _{SB2}	CMOS Standby Current (CMOS Inputs)	V _{DD} = Max.,	Com.	—	5	—	5	—	5	μA
		$\overline{CE} \geq V_{DD} - 0.2V$,	Ind.	—	10	—	10	—	10	
		V _{IN} ≥ V _{DD} - 0.2V, or	Auto.	—	30	—	30	—	30	
		V _{IN} ≤ 0.2V, f = 0	typ. ⁽²⁾	—	2	—	—	—	—	

Note:

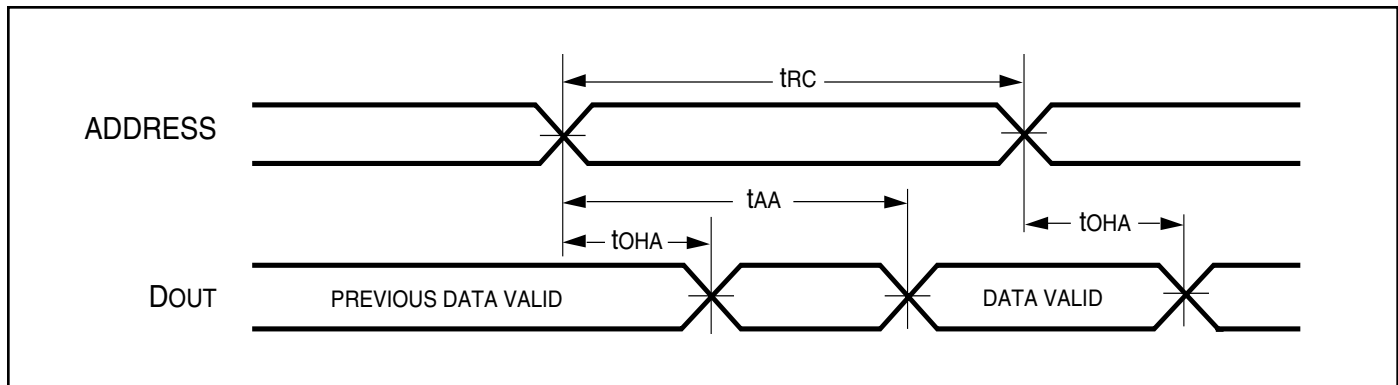
- At f = f_{MAX}, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.
- Typical values are measured at V_{DD} = 3.0V, T_A = 25°C and not 100% tested.

READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

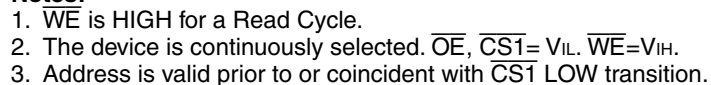
Symbol	Parameter	35 ns		45 ns		55 ns		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{RC}	Read Cycle Time	35	—	45	—	55	—	ns
t_{AA}	Address Access Time	—	35	—	45	—	55	ns
t_{OHA}	Output Hold Time	10	—	10	—	10	—	ns
t_{ACS1}	$\overline{CS1}$ Access Time	—	35	—	45	—	55	ns
t_{DOE}	$\overline{OE}$ Access Time	—	10	—	20	—	25	ns
$t_{HZOE}^{(2)}$	$\overline{OE}$ to High-Z Output	—	10	—	15	—	20	ns
$t_{LZOE}^{(2)}$	$\overline{OE}$ to Low-Z Output	3	—	5	—	5	—	ns
t_{HZCS1}	$\overline{CS1}$ to High-Z Output	0	10	0	15	0	20	ns
t_{LZCS1}	$\overline{CS1}$ to Low-Z Output	5	—	10	—	10	—	ns

Notes:

- Test conditions assume signal transition times of 5 ns or less, timing reference levels of 0.9V/1.5V, input pulse levels of 0.4 to $V_{DD}-0.2V/V_{DD}-0.3V$ and output loading specified in Figure 1.
- Tested with the load in Figure 2. Transition is measured ± 500 mV from steady-state voltage. Not 100% tested.

AC WAVEFORMS**READ CYCLE NO. 1^(1,2)** (Address Controlled) ($\overline{CS1} = \overline{OE} = V_{IL}$, $\overline{WE} = V_{IH}$)

READ CYCLE NO. 2^(1,3) ($\overline{\text{CS1}}$, $\overline{\text{OE}}$ Controlled)

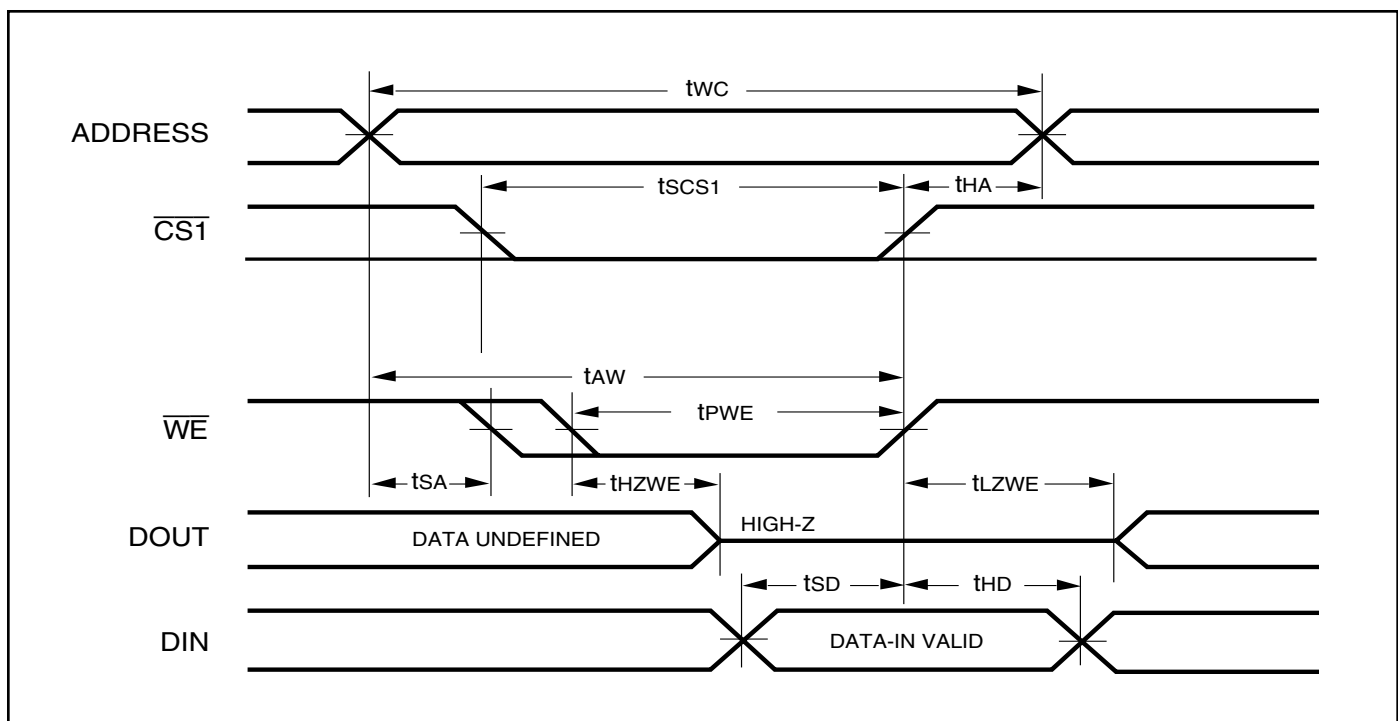


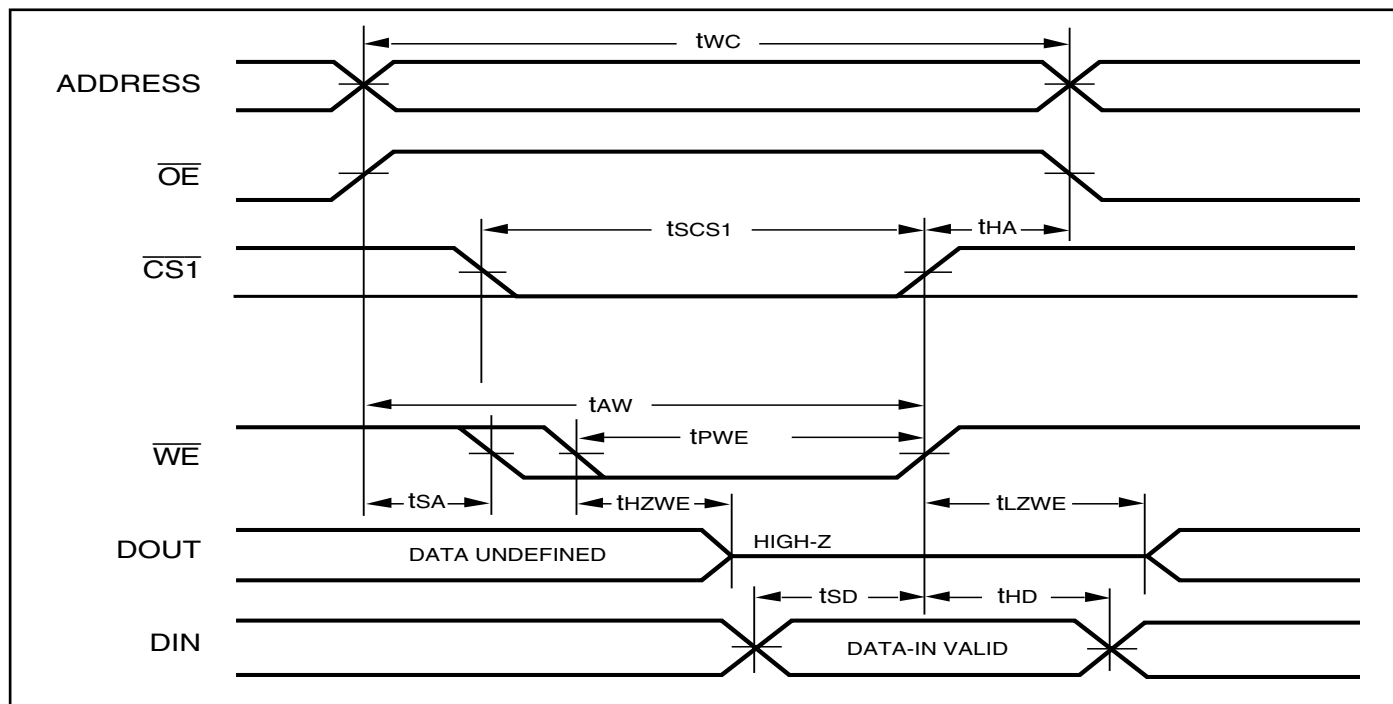
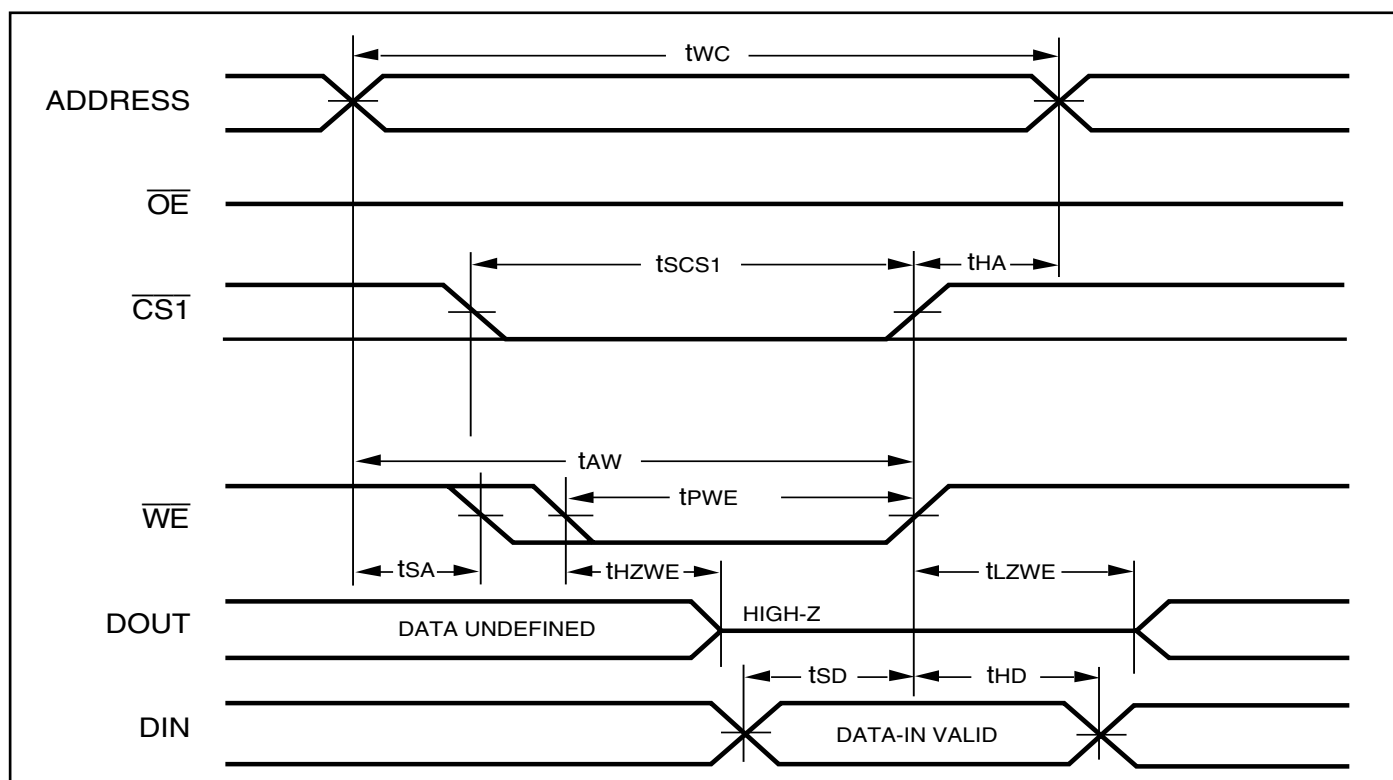
WRITE CYCLE SWITCHING CHARACTERISTICS^(1,2) (Over Operating Range)

Symbol	Parameter	35ns		45ns		55 ns		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{WC}	Write Cycle Time	35	—	45	—	55	—	ns
t _{SCS1}	$\overline{\text{CS1}}$ to Write End	25	—	35	—	45	—	ns
t _{AW}	Address Setup Time to Write End	25	—	35	—	45	—	ns
t _{HA}	Address Hold from Write End	0	—	0	—	0	—	ns
t _{SA}	Address Setup Time	0	—	0	—	0	—	ns
t _{PWE}	$\overline{\text{WE}}$ Pulse Width	25	—	35	—	40	—	ns
t _{SD}	Data Setup to Write End	20	—	20	—	25	—	ns
t _{HD}	Data Hold from Write End	0	—	0	—	0	—	ns
t _{HZWE} ⁽³⁾	$\overline{\text{WE}}$ LOW to High-Z Output	—	10	—	20	—	20	ns
t _{LZWE} ⁽³⁾	$\overline{\text{WE}}$ HIGH to Low-Z Output	3	—	5	—	5	—	ns

Notes:

1. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 0.9V/1.5V, input pulse levels of 0.4V to V_{DD}-0.2V/V_{DD}-0.3V and output loading specified in Figure 1.
2. The internal write time is defined by the overlap of $\overline{\text{CS1}}$ LOW and $\overline{\text{WE}}$ LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.
3. Tested with the load in Figure 2. Transition is measured ± 500 mV from steady-state voltage. Not 100% tested.

AC WAVEFORMS**WRITE CYCLE NO. 1** ($\overline{\text{CS1}}$ Controlled, $\overline{\text{OE}}$ = HIGH or LOW)

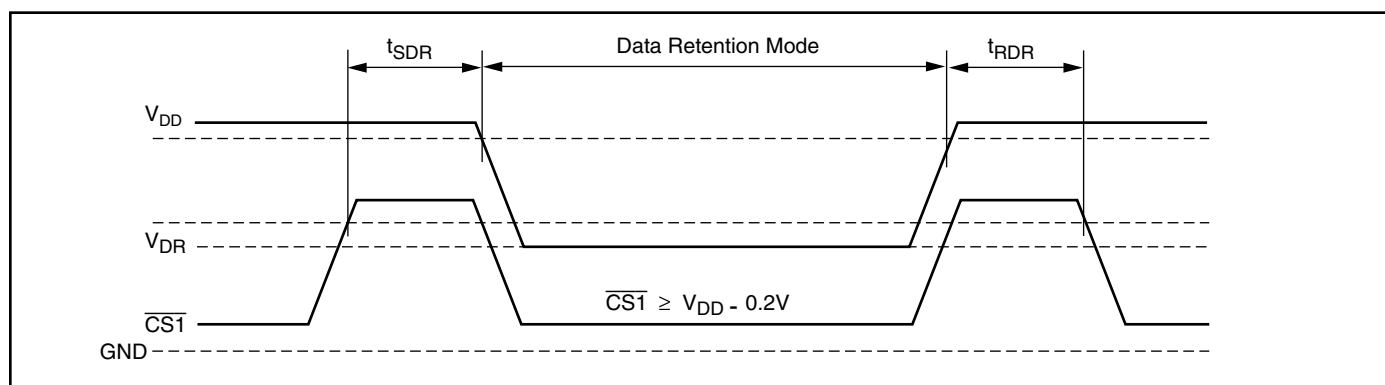
WRITE CYCLE NO. 2 ($\overline{WE}$ Controlled: $\overline{OE}$ is HIGH During Write Cycle)

WRITE CYCLE NO. 3 ($\overline{WE}$ Controlled: $\overline{OE}$ is LOW During Write Cycle)


DATA RETENTION SWITCHING CHARACTERISTICS

Symbol	Parameter	Test Condition	Min.	Max.	Unit
V_{DR}	V_{DD} for Data Retention	See Data Retention Waveform	1.2	3.6	V
I_{DR}	Data Retention Current	$V_{DD} = 1.2V$, $\overline{CS1} \geq V_{DD} - 0.2V$	Com. Ind. Auto. typ. ⁽¹⁾	3 7 20	μA
			1		
t_{SDR}	Data Retention Setup Time	See Data Retention Waveform	0	—	ns
t_{RDR}	Recovery Time	See Data Retention Waveform	t_{RC}	—	ns

Note: 1. Typical values are measured at $V_{DD} = 3.0V$, $T_A = 25^\circ C$ and not 100% tested.

DATA RETENTION WAVEFORM ($\overline{CS1}$ Controlled)



IS62WV5128DALL/DBLL, IS65WV5128DALL/DBLL

ORDERING INFORMATION

IS62WV5128DALL (1.65V-2.2V)

Industrial Range: –40°C to +85°C

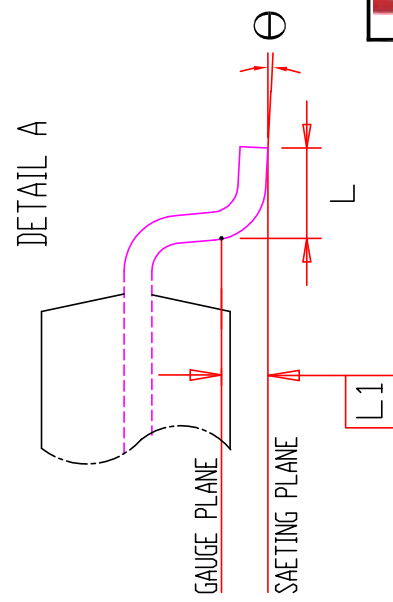
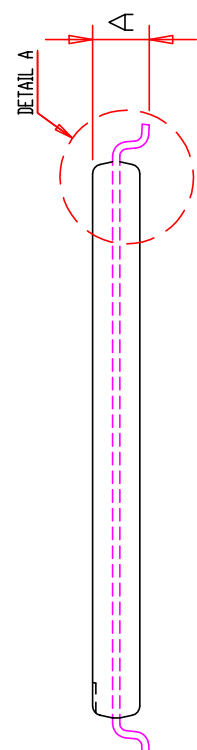
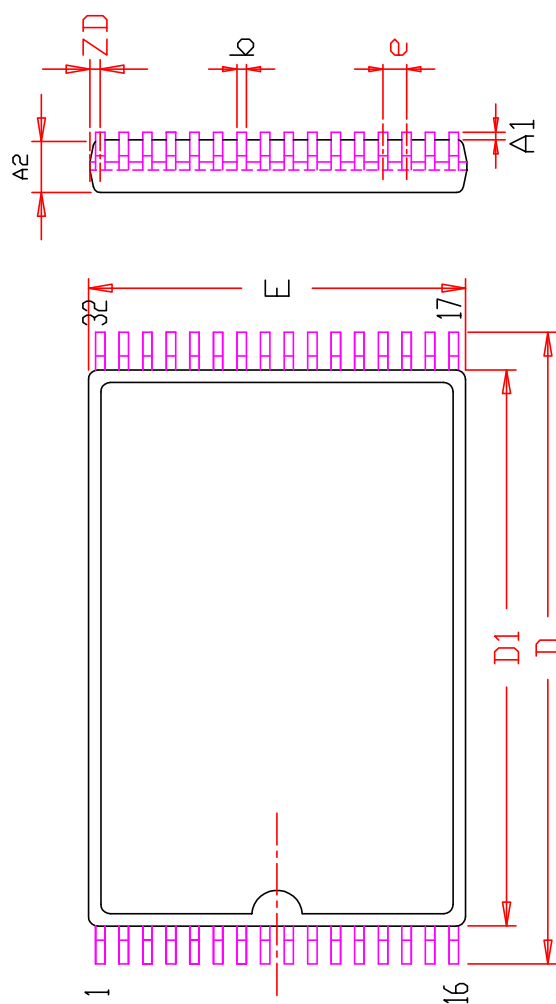
Speed (ns)	Order Part No.	Package
55	IS62WV5128DALL-55TI	TSOP, TYPE I (8 x 20 mm)
	IS62WV5128DALL-55TLI	TSOP, TYPE I, Lead-free (8 x 20 mm)
55	IS62WV5128DALL-55T2I	TSOP, TYPE II
	IS62WV5128DALL-55T2LI	TSOP, TYPE II, Lead-free
55	IS62WV5128DALL-55HI	sTSOP, TYPE I (8 x 13.4 mm)
	IS62WV5128DALL-55HLI	sTSOP, TYPE I, Lead-free (8 x 13.4 mm)
55	IS62WV5128DALL-55BI	mini BGA (6mmx8mm)
	IS62WV5128DALL-55BLI	mini BGA (6mmx8mm), Lead-free

ORDERING INFORMATION

IS62WV5128BLL (2.3V - 3.6V)

Industrial Range: –40°C to +85°C

Speed (ns)	Order Part No.	Package
45	IS62WV5128DBLL-45TI	TSOP, TYPE I (8 x 20 mm)
45	IS62WV5128DBLL-45TLI	TSOP, TYPE I, Lead-free (8 x 20 mm)
45	IS62WV5128DBLL-45QLI	SOP, Lead-free
45	IS62WV5128DBLL-45T2I	TSOP, TYPE II
45	IS62WV5128DBLL-45T2LI	TSOP, TYPE II, Lead-free
45	IS62WV5128DBLL-45HI	sTSOP, TYPE I (8 x 13.4 mm)
45	IS62WV5128DBLL-45HLI	sTSOP, TYPE I, Lead-free (8 x 13.4 mm)
45	IS62WV5128DBLL-45BI	mini BGA (6mmx8mm)
45	IS62WV5128DBLL-45BLI	mini BGA (6mmx8mm), Lead-free

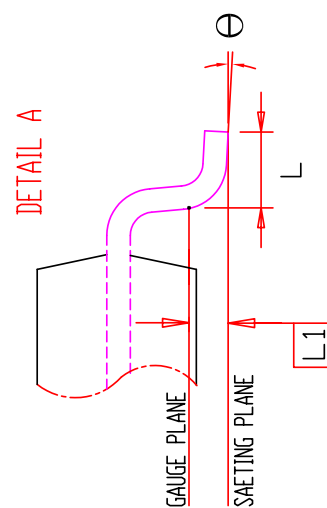
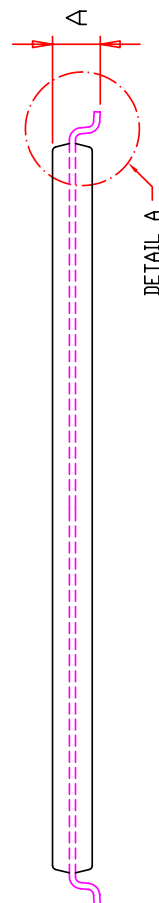
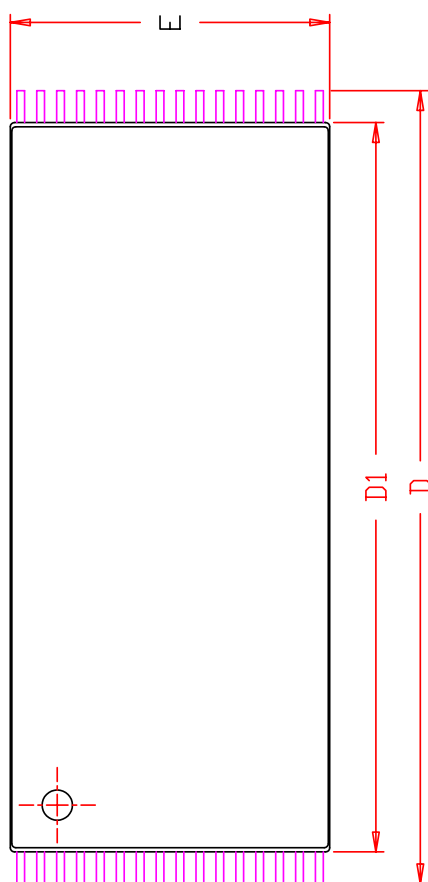
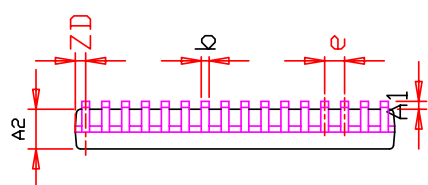


NOTE :

- 1. CONTROLLING DIMENSION : MM
- 2. DIMENSION D1 AND E DO NOT INCLUDE MOLD PROTRUSION.
- 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.
- 4. Reference Document : JEDEC MO-183

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN	NDM	MAX	MIN	NDM	MAX
A	0.95		1.20	0.037		0.047
A1	0.05		0.15	0.002		0.008
A2	0.90		1.05	0.035		0.041
b	0.16		0.27	0.006		0.011
D	13.10	13.40	13.70	0.516	0.528	0.539
D1	11.70	11.80	11.90	0.461	0.465	0.469
E	7.90	8.00	8.10	0.311	0.315	0.319
e	0.50 BSC.			0.020 BSC.		
L	0.30	0.50	0.70	0.012	0.020	0.028
L1	0.25 BSC.			0.010 BSC.		
ZD	0.25 REF.			0.010 REF.		
Θ	0	3°	5°	0	3°	5°

	TITLE	32L 8x13.4mm TSOP-1 Package Outline	REV.	E	DATE	04/24/2008



NOTE :

1. Controlling dimension : mm
2. Dimension D1 adn E do not include mold protrusion .
3. Dimension b does not include dambar protrusion/intrusion.
4. Formed leads shall be planar with respect to one another within 0.1mm at the seating plane after final test.

SYMBOL	DIMENSION IN MM		
	MIN	NOM	MAX
A	1.00		1.20
A1	0.05		0.20
A2	0.95	1.00	1.05
b	0.17		0.27
D	19.80	20.00	20.20
D1	18.30	18.40	18.50
E	7.80	8.00	8.20
e		0.50 BSC.	
L	0.40		0.70
L1		0.25 BSC.	
ZD		0.25 REF.	
Θ	0	5°	8°

ISSI®

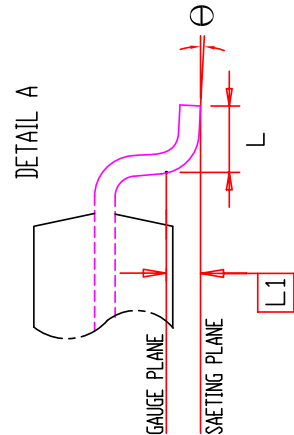
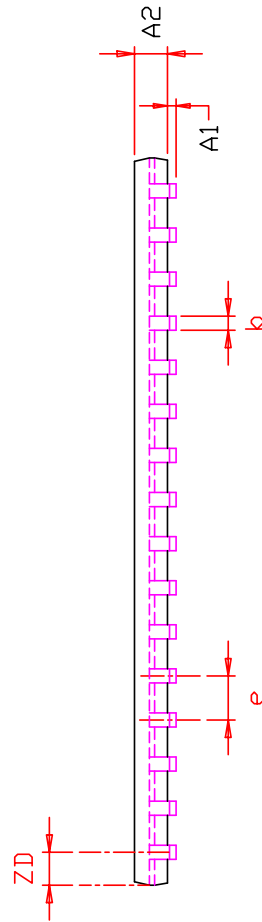
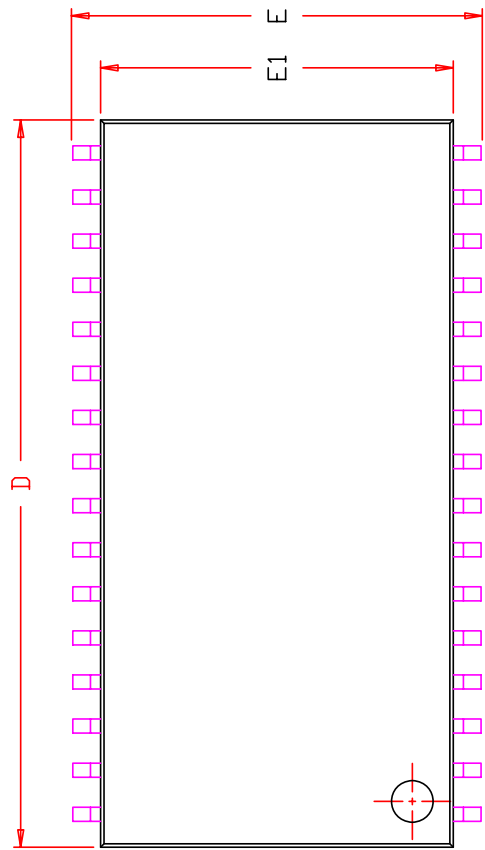
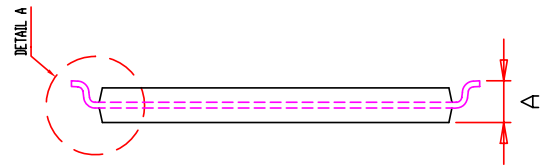
32L 8x20mm TSOP-1
Package Outline

REV.

E

DATE

06/08/2006

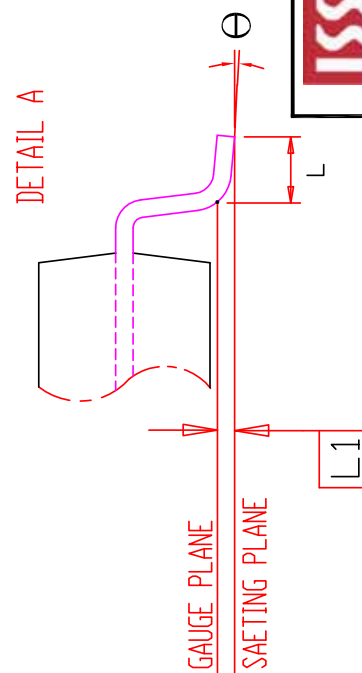
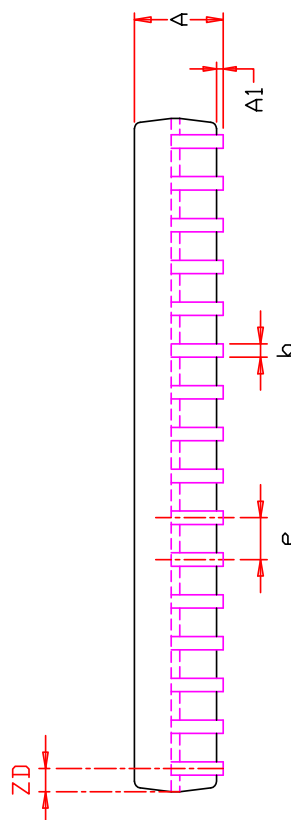
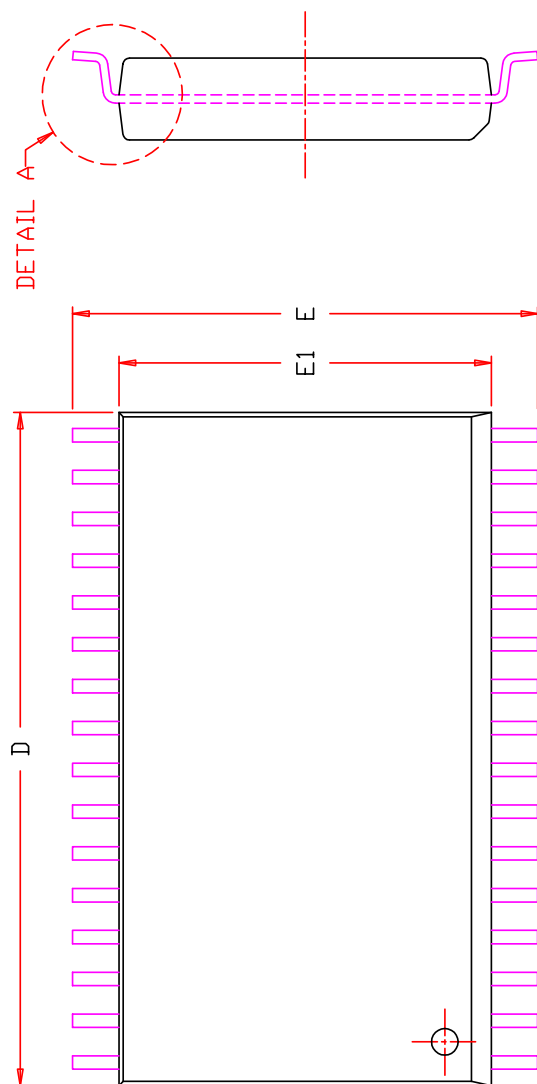


NOTE :

- 1. CONTROLLING DIMENSION : MM
- 2. DIMENSION D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
- 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.00		1.20	0.039		0.047
A1	0.05		0.15	0.002		0.006
A2	0.95	1.00	1.05	0.037	0.039	0.041
b	0.30		0.52	0.012		0.020
D	20.82	20.95	21.08	0.820	0.825	0.830
E	11.56	11.76	11.96	0.455	0.463	0.471
E1	10.03	10.16	10.29	0.395	0.400	0.405
e	1.27 BSC.			0.050 BSC.		
L	0.40	0.50	0.60	0.016	0.020	0.024
L1	0.25 BSC.			0.010 BSC.		
ZD	0.95 REF.			0.037 REF.		
θ	0		8°	0		8°

	TITLE	32L 400mil TSOP-2 Package Outline	REV.	E	DATE	06/23/2009



NOTE :

1. CONTROLLING DIMENSION : MM
2. DIMENSION D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	2.62		3.12	0.103		0.123
A1	0.05		0.30	0.002		0.012
b	0.33		0.51	0.013		0.020
D	20.24		20.75	0.797		0.817
E	13.79		14.45	0.543		0.569
E1	11.18		11.43	0.440		0.450
e	1.27 BSC.			0.050 BSC.		
L	0.38		1.27	0.015		0.050
L1	0.25 BSC.			0.010 BSC.		
ZD	0.725 REF.			0.029 REF.		
Θ	0		8°	0		8°



TITLE

32L 450mil SOP
Package Outline

REV.

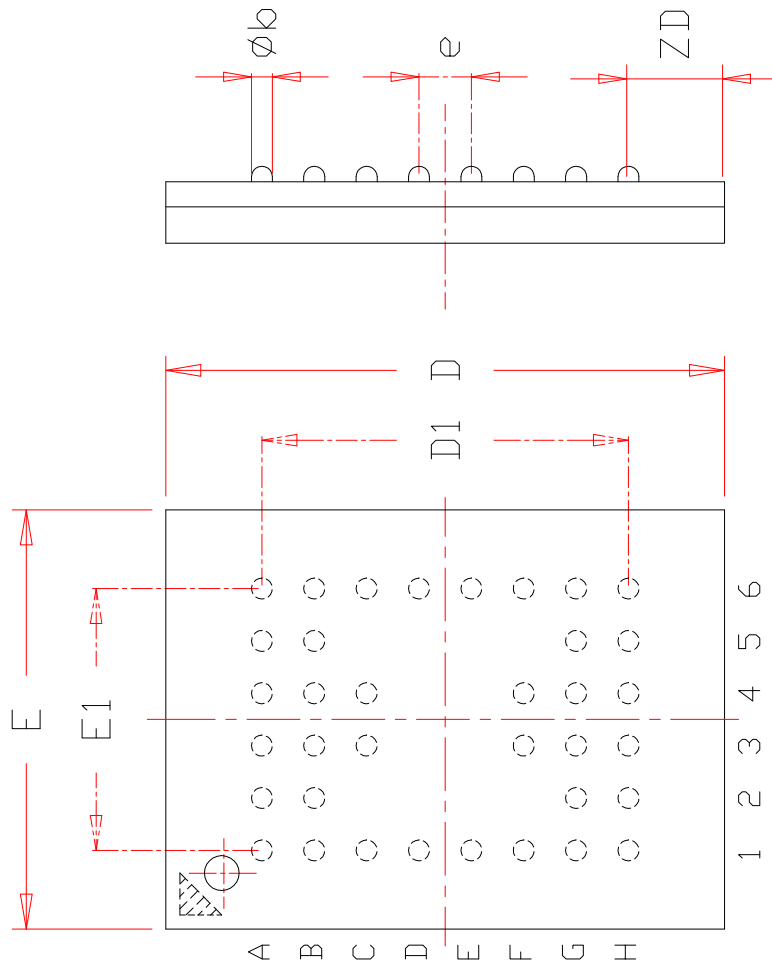
D

DATE

04/20/2009



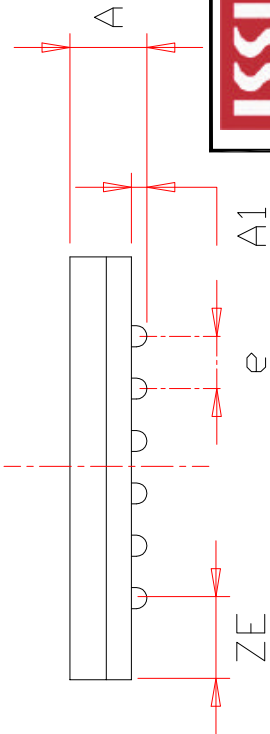
TOP VIEW



NOTE :

- 1. CONTROLLING DIMENSION : MM .
- 2. Reference document : JEDEC MO-207

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A			1.20			0.047
A1	0.20		0.30	0.008		0.012
øb	0.30	0.35	0.40	0.012	0.014	0.016
D	7.90	8.00	8.10	0.311	0.315	0.319
D1	5.25 BSC.			0.207 BSC.		
E	5.90	6.00	6.10	0.232	0.236	0.240
E1	3.75 BSC.			0.148 BSC.		
e	0.75 BSC.			0.030 BSC.		
ZD	1.375 REF.			0.054 REF.		
ZE	1.125 REF.			0.044 REF.		



36/48L 6x8mm TF-BGA
Package Outline

TITLE

REV.

E

DATE

08/12/2008